



SOT1649-1

VFLGA64, plastic, very thin fine-pitch land grid array package;
64 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.91 mm body

2 July 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	VFLGA64
Package style descriptive code	VFLGA (very thin fine-pitch land grid array package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	31-05-2019
Manufacturer package code	98ASA00694D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	6.9	7	7.1	mm
package width	6.9	7	7.1	mm
package height	0.84	0.91	0.98	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	64	-	



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2 Package outline

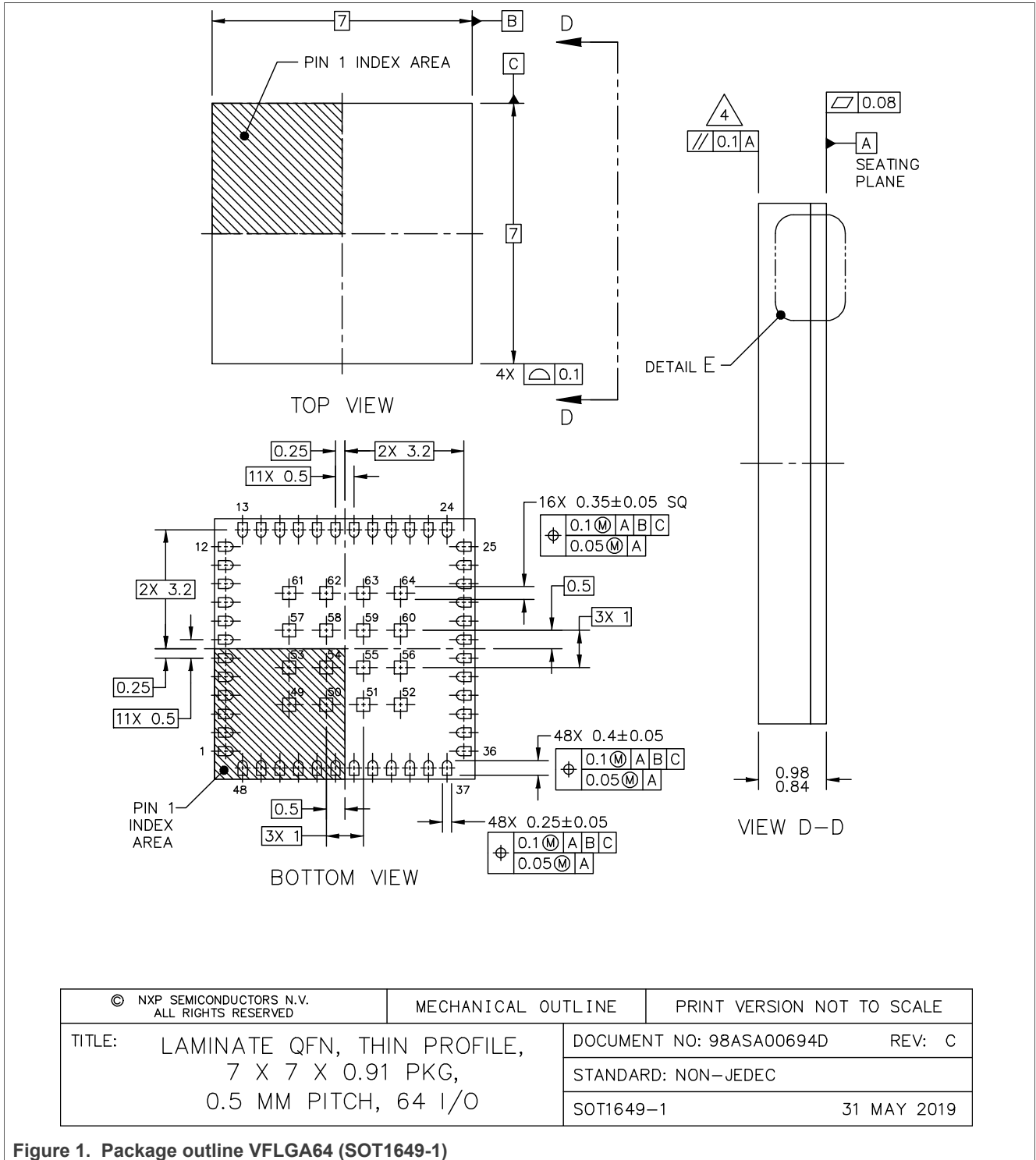


Figure 1. Package outline VFLGA64 (SOT1649-1)

VFLGA64, plastic, very thin fine-pitch land grid array package; 64 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.91 mm body

3 Soldering

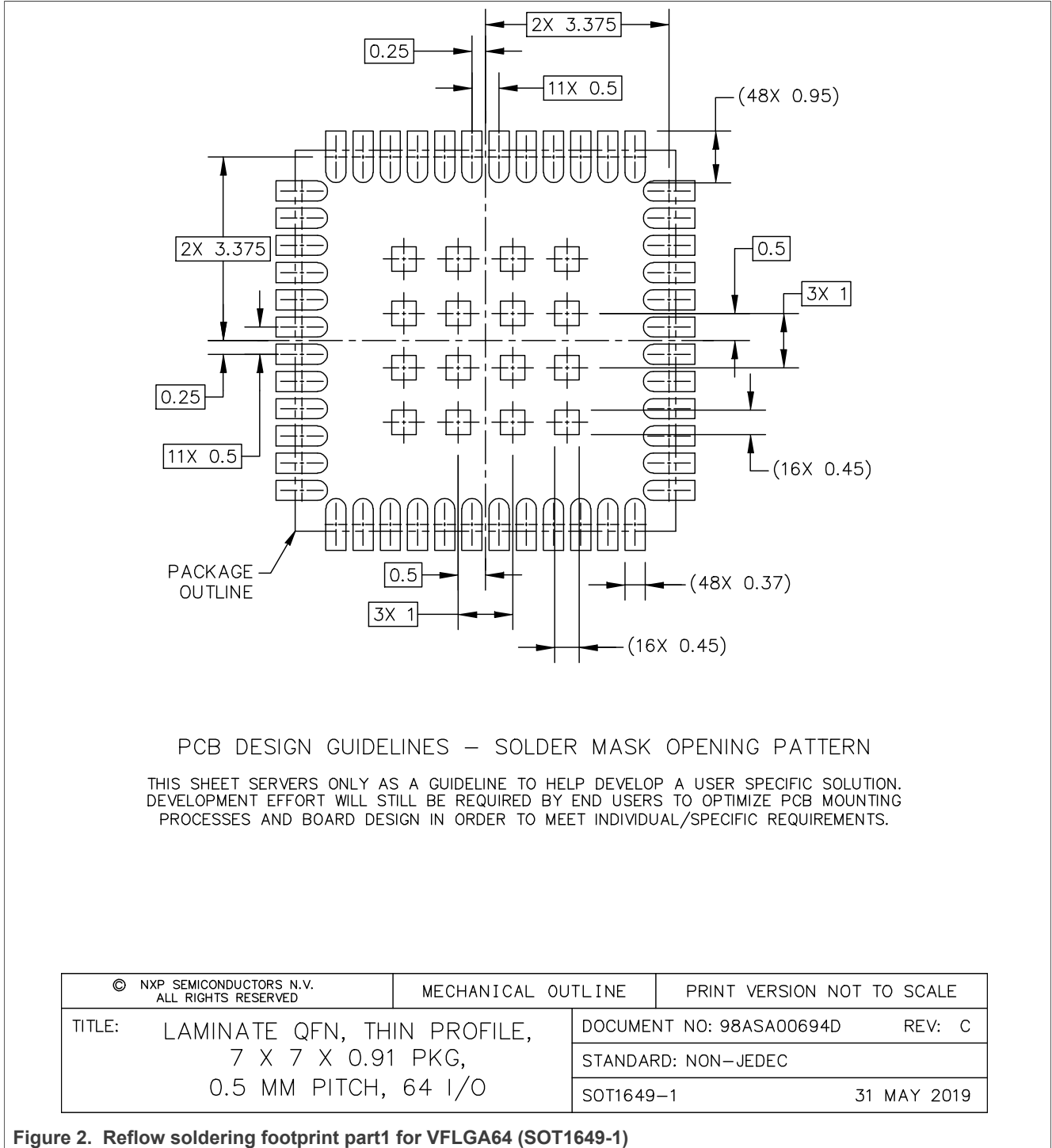
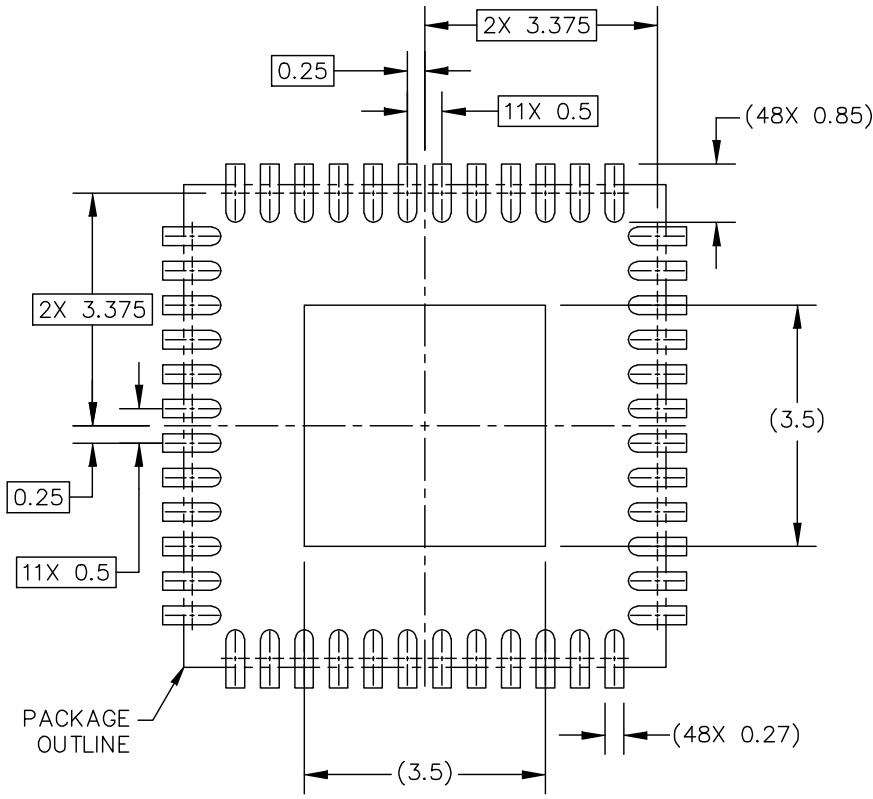


Figure 2. Reflow soldering footprint part1 for VFLGA64 (SOT1649-1)

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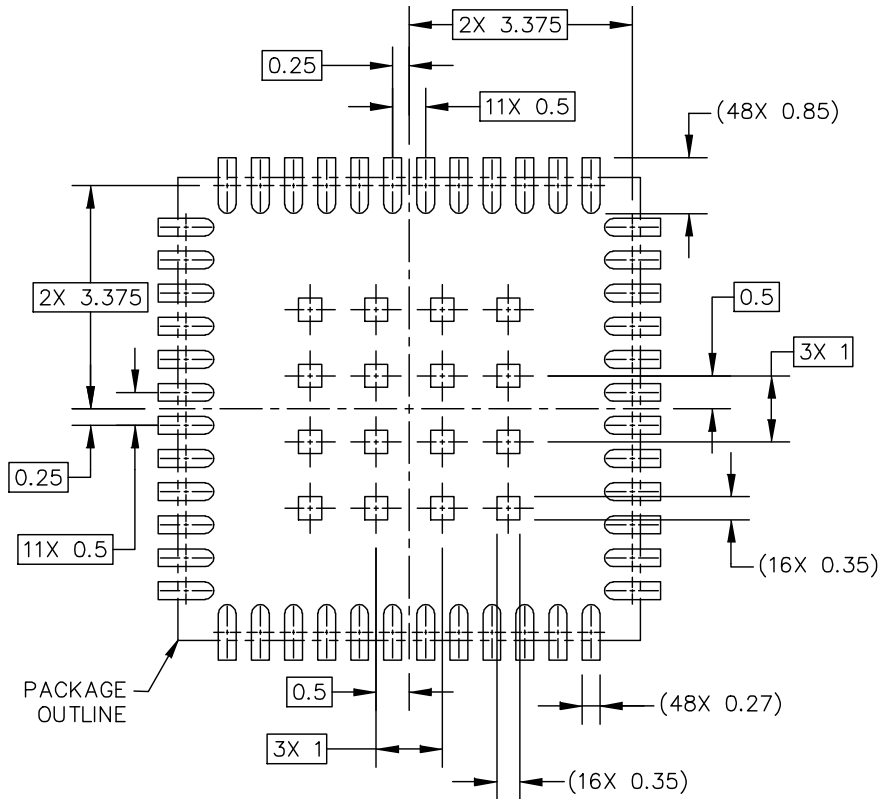
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TITLE: LAMINATE QFN, THIN PROFILE, 7 X 7 X 0.91 PKG, 0.5 MM PITCH, 64 I/O		DOCUMENT NO: 98ASA00694D	REV: C
		STANDARD: NON-JEDEC	
		SOT1649-1	31 MAY 2019

Figure 3. Reflow soldering footprint part2 for VFLGA64 (SOT1649-1)

VFLGA64, plastic, very thin fine-pitch land grid array package; 64 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.91 mm body



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for VFLGA64 (SOT1649-1)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DIMENSION APPLIES TO ALL LEADS.
4. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note VFLGA64 (SOT1649-1)

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4 Legal information

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